



# 立体成型基板用ソルダーレジスト

## MD-300 Series

- 3D-MID基板の作成方法 Process flow of 3D-MID



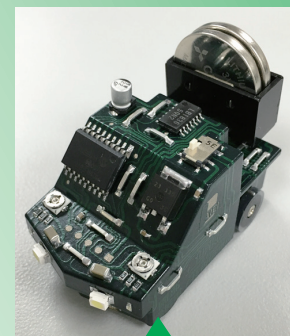
成型樹脂  
Molding

回路形成 Patterning  
+  
銅めっき Copper plating

SR塗布  
Resist coating

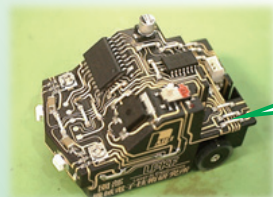
レーザー開口 Leaser trimming  
+  
金めっき E' less Ni/Au Plating

部品実装  
Device mounting



- ソルダーレジストの役割 Roles of Solder resist

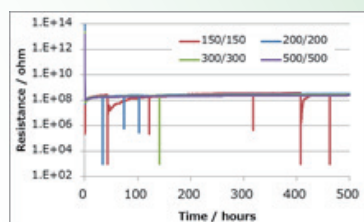
実装時の流れ防止  
Prevention of solder outflow



金めっき削減によるコストダウン  
Cost reduction by reducing gold plating area

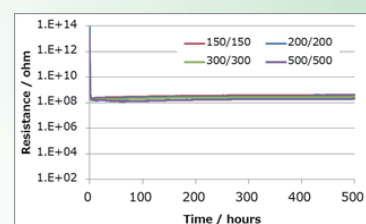


高絶縁信頼性  
High insulation reliability



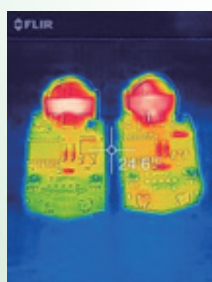
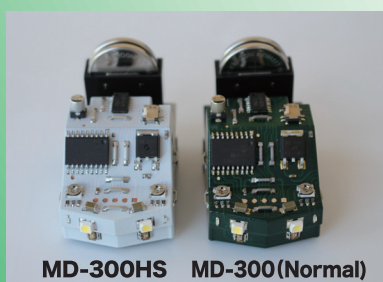
電気特性(85deg.C/85%RH/DC30V 基材:PA)  
L/S=150/150, 200/200, 300/300, 500/500 um

ソルダーレジストが  
あれば  
After coating  
Solder resist



## MD-300 HS Series

- 放熱仕様のレジストもご用意しております。  
Solder resist for heat dissipation is newly released to 3D-MID application.



Effect of heat dissipation  
(Approx. 10°C down)



TAIYO INK MFG. CO., LTD.